

# MOCD223M

## Dual Channel Phototransistor Small Outline Surface Mount Optocouplers

### Features

- U.L. Recognized (File #E90700, Volume 2)
- VDE Recognized (File #13616) (add option "V" for VDE approval, i.e., MOCD223VM)
- Convenient Plastic SOIC-8 Surface Mountable Package Style
- High Current Transfer Ratio of 500% Minimum at  $I_F = 1\text{mA}$
- Minimum  $BV_{CEO}$  of 30 Volts Guaranteed
- Standard SOIC-8 Footprint, with 0.050" Lead Spacing
- Compatible with Dual Wave, Vapor Phase and IR Reflow Soldering
- High Input-Output Isolation Voltage of 2500  $V_{AC(rms)}$  Guaranteed

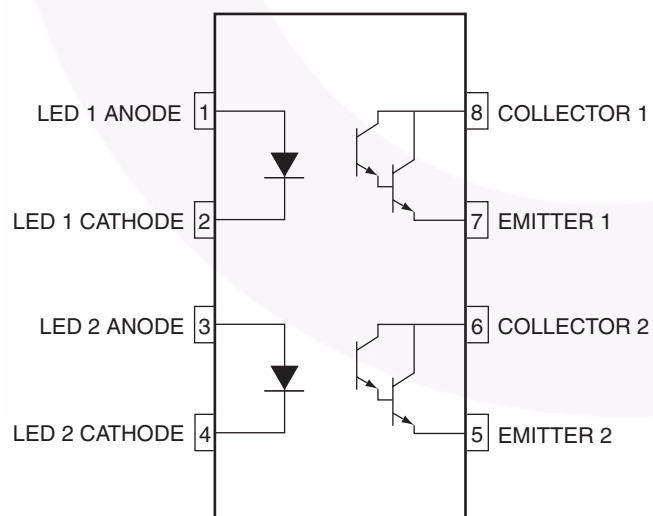
### Applications

- Interfacing and coupling systems of different potentials and impedances
- General purpose switching circuits
- Monitor and detection circuits

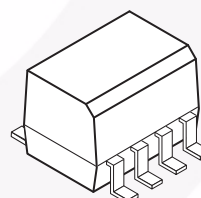
### Description

The MOCD223M consist of two gallium arsenide infrared emitting diodes optically coupled to two monolithic silicon phototransistor darlington detectors, in a surface mountable, small outline plastic package. It is ideally suited for high density applications that require low input current and eliminates the need for through-the-board mounting.

### Schematic



### Package Outline



**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  Unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Rating	Value	Unit
<b>EMITTER</b>			
$I_F$	Forward Current – Continuous	60	mA
$I_F$ (pk)	Forward Current – Peak (PW = 100 $\mu$ s, 120pps)	1.0	A
$V_R$	Reverse Voltage	6.0	V
$P_D$	LED Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	90 0.8	mW mW/ $^\circ\text{C}$
<b>DETECTOR</b>			
$V_{CEO}$	Collector-Emitter Voltage	30	V
$V_{CBO}$	Collector-Base Voltage	70	V
$V_{ECO}$	Emitter-Collector Voltage	7.0	V
$I_C$	Collector Current-Continuous	150	mA
$P_D$	Detector Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	150 1.76	mW mW/ $^\circ\text{C}$
<b>TOTAL DEVICE</b>			
$V_{ISO}$	Input-Output Isolation Voltage <sup>(1,2,3)</sup> (f = 60Hz, t = 1 min. Duration)	2500	Vac(rms)
$P_D$	Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	250 2.94	mW mW/ $^\circ\text{C}$
$T_A$	Ambient Operating Temperature Range	-40 to +100	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-40 to +150	$^\circ\text{C}$
$T_L$	Lead Soldering Temperature (1/16" from case, 10 sec. duration)	260	$^\circ\text{C}$

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Unit
<b>EMITTER</b>						
$V_F$	Input Forward Voltage	$I_F = 1.0\text{mA}$		1.25	1.3	V
$I_R$	Reverse Leakage Current	$V_R = 6.0\text{V}$		0.001	100	$\mu\text{A}$
$C_{IN}$	Capacitance			18		pF
<b>DETECTOR</b>						
$I_{CEO1}$	Collector-Emitter Dark Current	$V_{CE} = 5.0\text{V}, T_A = 25^\circ\text{C}$		1.0	50	nA
$I_{CEO2}$		$V_{CE} = 5.0\text{V}, T_A = 100^\circ\text{C}$		1.0		$\mu\text{A}$
$BV_{CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 100\mu\text{A}$	30	90		V
$BV_{ECO}$	Emitter-Collector Breakdown Voltage	$I_E = 100\mu\text{A}$	7.0	10		V
$C_{CE}$	Collector-Emitter Capacitance	$f = 1.0\text{MHz}, V_{CE} = 0$		5.5		pF
<b>COUPLED</b>						
CTR	Collector-Output Current <sup>(4)</sup>	$I_F = 1.0\text{mA}, V_{CE} = 5\text{V}$	500	1000		%
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 500\mu\text{A}, I_F = 1.0\text{mA}$			1.0	V
$t_{on}$	Turn-On Time	$I_F = 5.0\text{mA}, V_{CC} = 10\text{V}, R_L = 100\Omega$ (Fig 6.)		8		$\mu\text{s}$
$t_{off}$	Turn-Off Time	$I_F = 5.0\text{mA}, V_{CC} = 10\text{V}, R_L = 100\Omega$ (Fig 6.)		55		$\mu\text{s}$
$t_r$	Rise Time	$I_F = 5.0\text{mA}, V_{CC} = 10\text{V}, R_L = 100\Omega$ (Fig 6.)		6		$\mu\text{s}$
$t_f$	Fall Time	$I_F = 5.0\text{mA}, V_{CC} = 10\text{V}, R_L = 100\Omega$ (Fig 6.)		45		$\mu\text{s}$
$V_{ISO}$	Isolation Surge Voltage <sup>(1,2,3)</sup>	$f = 60\text{Hz}, t = 1 \text{ min.}$	2500			Vac(rms)
$R_{ISO}$	Isolation Resistance <sup>(2)</sup>	$V_{I-O} = 500\text{V}$	$10^{11}$			$\Omega$
$C_{ISO}$	Isolation Capacitance <sup>(2)</sup>	$V_{I-O} = 0\text{V}, f = 1 \text{ MHz}$		0.2		pF

\*Typical values at  $T_A = 25^\circ\text{C}$ **Notes:**

1. Isolation Surge Voltage,  $V_{ISO}$ , is an internal device dielectric breakdown rating.
2. For this test, Pins 1, 2, 3 and 4 are common and Pins 5, 6, 7 and 8 are common.
3.  $V_{ISO}$  rating of 2500  $V_{AC(rms)}$  for  $t = 1 \text{ min.}$  is equivalent to a rating of 3,000  $V_{AC(rms)}$  for  $t = 1 \text{ sec.}$
4. Current Transfer Ratio (CTR) =  $I_C / I_F \times 100\%$

## Typical Performance Curves

Fig. 1 LED Forward Voltage vs. Forward Current

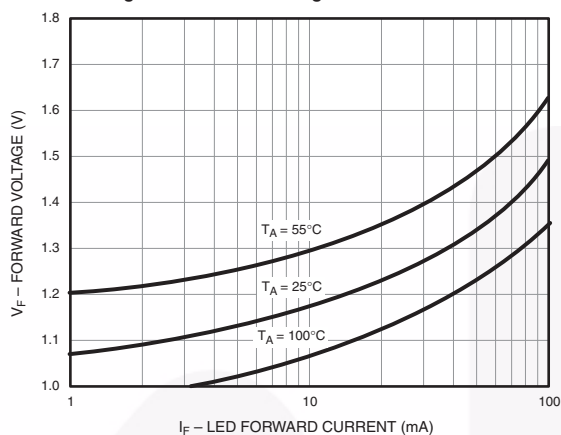


Fig. 2 Output Current vs. Input Current

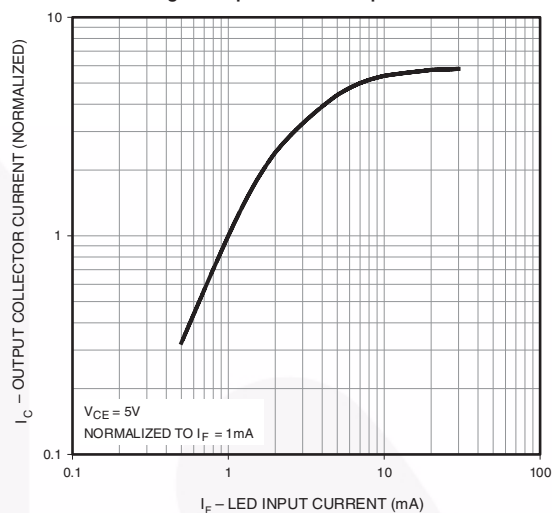


Fig. 3 Output Current vs. Ambient Temperature

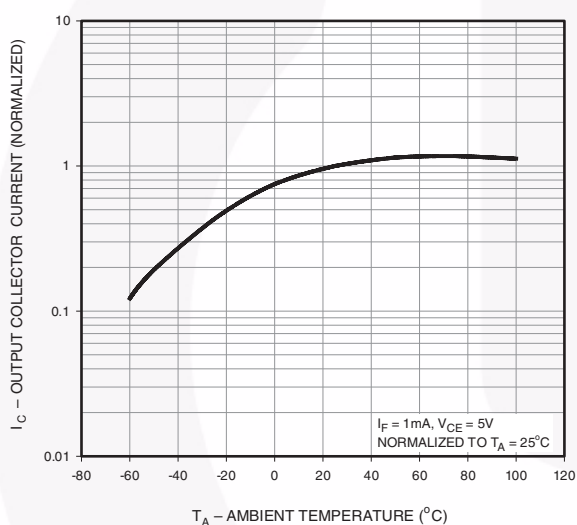


Fig. 4 Output Current vs. Collector - Emitter Voltage

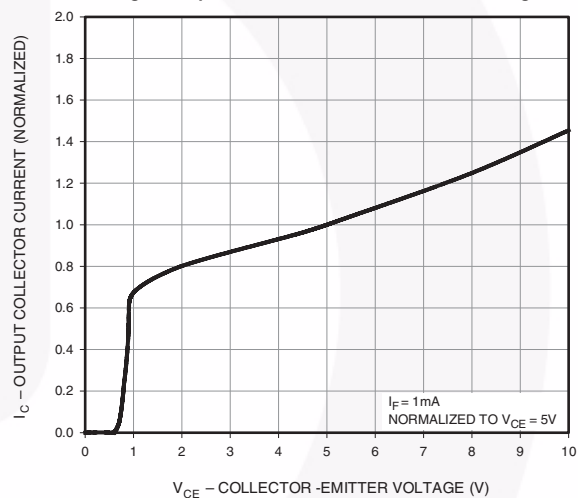
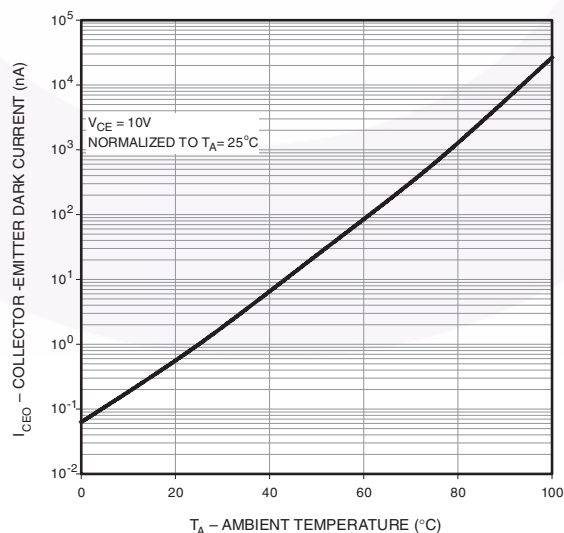


Fig. 5 Dark Current vs. Ambient Temperature



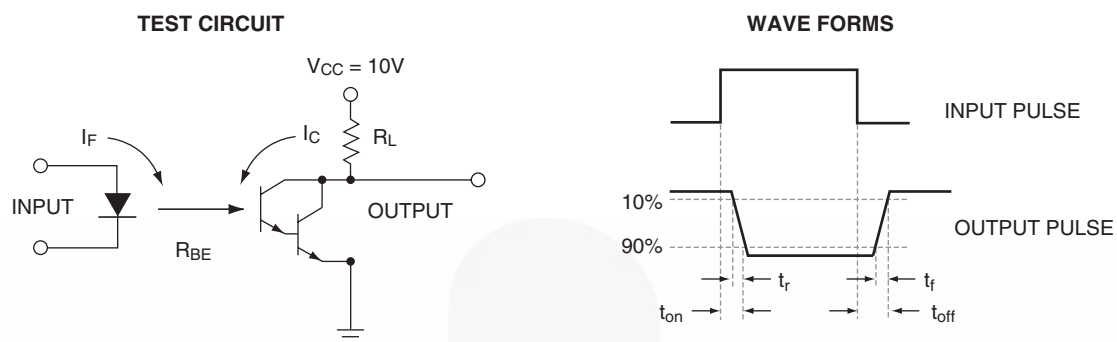
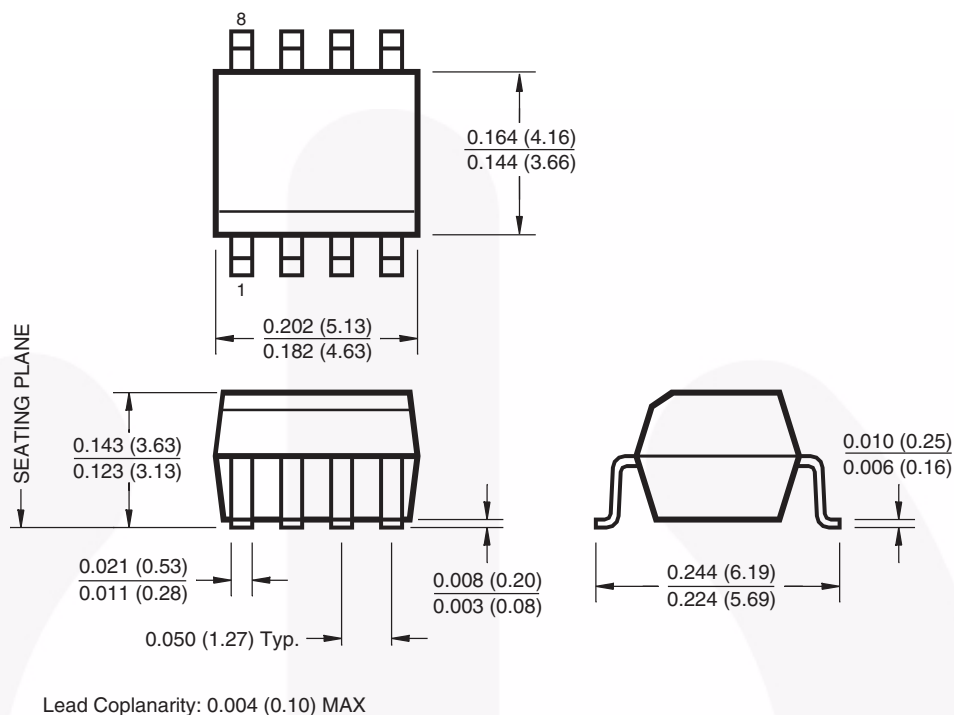


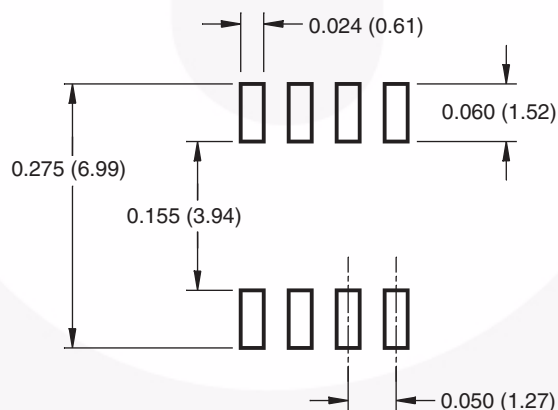
Figure 6. Switching Time Test Circuit and Waveform

## Package Dimensions

### 8-pin SOIC Surface Mount



### Recommended Pad Layout



Dimensions in inches (mm).

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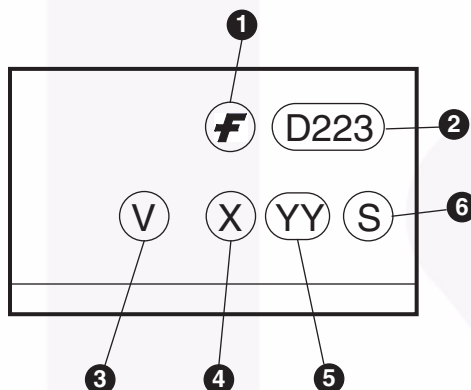
Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

## Ordering Information

Option	Order Entry Identifier	Description
V	V	VDE 0884
R2	R2	Tape and reel (2500 units per reel)
R2V	R2V	VDE 0884, Tape and reel (2500 units per reel)

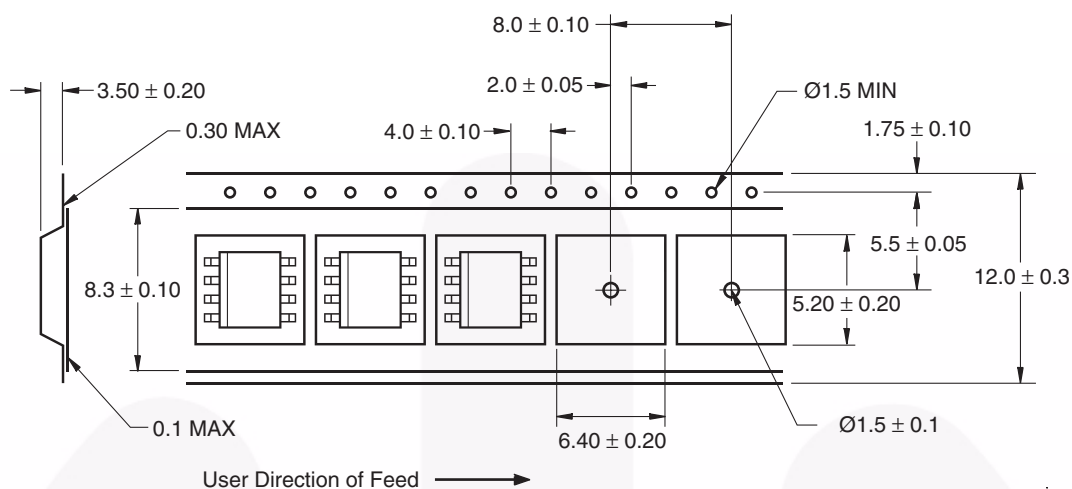
## Marking Information



### Definitions

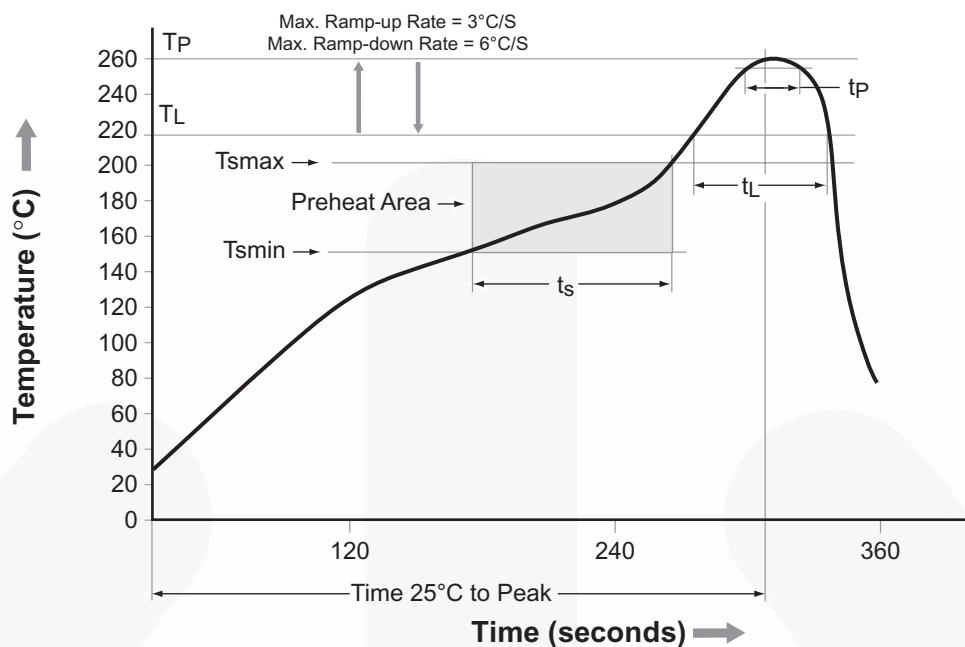
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

# Carrier Tape Specifications





## Reflow Profile









Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60–120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>p</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60–150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>p</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>p</sub> to T <sub>L</sub> )	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.



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